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MC10123

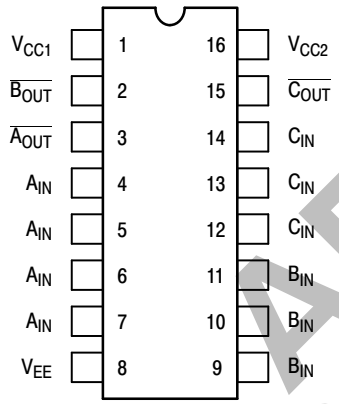
Triple 4-3-3-Input Bus Driver

The MC10123 consists of three NOR gates designed for bus driving applications on card or between cards. Output low logic levels are specified with V_{OL} = –2.1 Vdc so that the bus may be terminated to –2.0 Vdc. The gate output, when low, appears as a high impedance to the bus, because the output emitter– followers of the MC10123 are "turned–off." This eliminates discontinuities in the characteristic impedance of the bus.

The V_{OH} level is specified when driving a 25–ohm load terminated to –2.0 Vdc, the equivalent of a 50–ohm bus terminated at both ends. Although 25 ohms is the lowest characteristic impedance that can be driven by the MC10123, higher impedance values may be used with this part. A typical 50–ohm bus is shown in Figure 1.

- P_D = 310 mW typ/pkg (No Load)
- t_{pd} = 3.0 ns typ
- t_r, t_f = 2.5 ns typ (20%–80%)

DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

LOGIC DIAGRAM

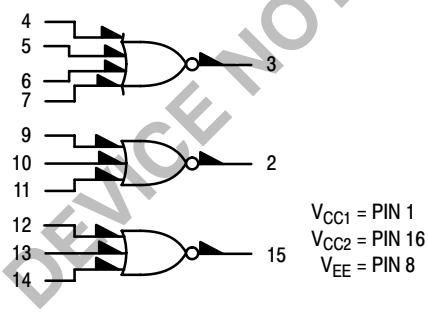
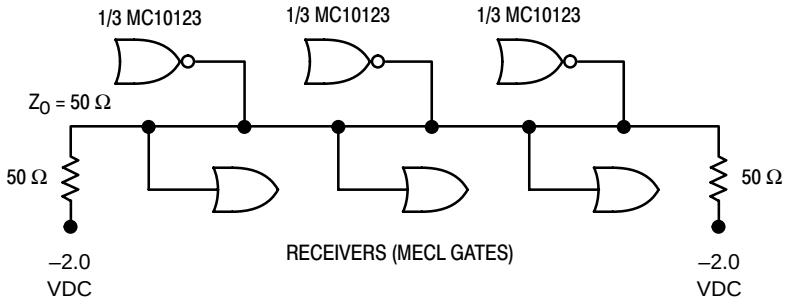


FIGURE 1 — 50–OHM BUS DRIVER (TYPICAL APPLICATION)



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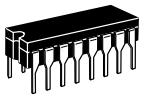
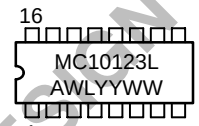
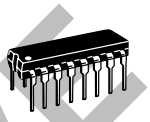
MARKING DIAGRAMS

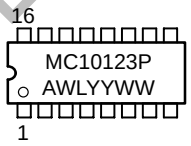


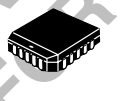
CDIP–16
L SUFFIX
CASE 620



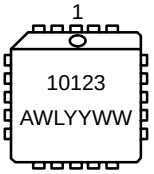


PDIP–16
P SUFFIX
CASE 648





PLCC–20
FN SUFFIX
CASE 775



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10123L	CDIP–16	25 Units / Rail
MC10123P	PDIP–16	25 Units / Rail
MC10123FN	PLCC–20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Pin Under Test	Test Limits							Unit
			–30°C		+25°C			+85°C		
			Min	Max	Min	Typ	Max	Min	Max	
Power Supply Drain Current	I_E	8		82		71	75		82	mAdc
Input Current	I_{inH}	4		350			220		220	μAdc
	I_{inL}	4			0.5					μAdc
Output Voltage Logic 1	V_{OH}	3	–1.060	–0.890	–0.960		–0.810	–0.890	–0.700	Vdc
Output Voltage Logic 0	V_{OL}	3	–2.100	–2.030	–2.100		–2.030	–2.100	–2.030	Vdc
Threshold Voltage Logic 1	V_{OHA}	3	–1.080		–0.980			–0.910		Vdc
Threshold Voltage Logic 0	V_{OLA}	3		–2.100			–2.100		–2.100	Vdc
Switching Times (50Ω Load)										ns
Propagation Delay	t_{4+3-}	3	1.2	4.6	1.2	3.0	4.4	1.2	4.8	
	t_{4-3+}	3	1.2	4.6	1.2	3.0	4.4	1.2	4.8	
Rise Time (20 to 80%)	t_{3+}	3	1.0	3.7	1.0	2.5	3.5	1.0	3.9	
Fall Time (20 to 80%)	t_{3-}	3	1.0	3.7	1.0	2.5	3.5	1.0	3.9	

ELECTRICAL CHARACTERISTICS (continued)

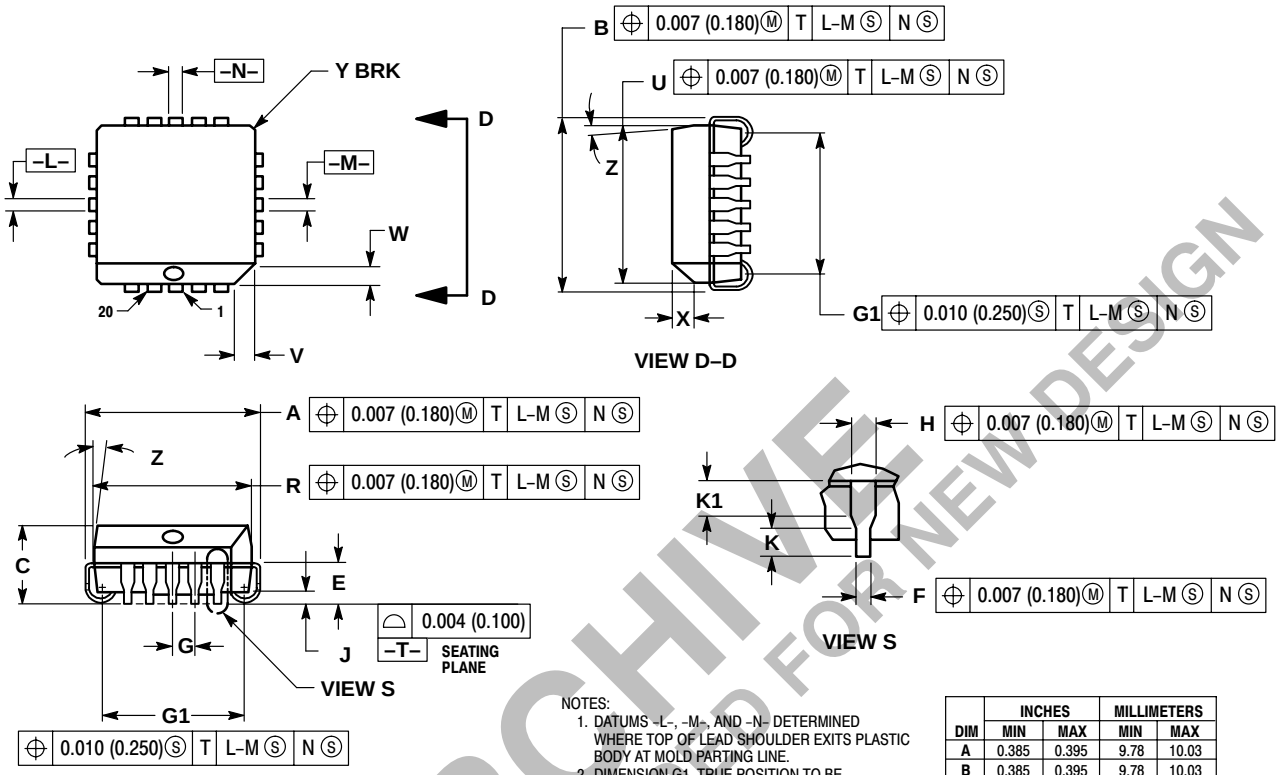
@ Test Temperature	TEST VOLTAGE VALUES (Volts)				
	V_{IHmax}	V_{ILmin}	V_{IHAmin}	V_{ILAmax}	V_{EE}
–30°C	–0.890	–1.890	–1.205	–1.500	–5.2
+25°C	–0.810	–1.850	–1.105	–1.475	–5.2
+85°C	–0.700	–1.825	–1.035	–1.440	–5.2

Characteristic	Symbol	Pin Under Test	TEST VOLTAGE APPLIED TO PINS LISTED BELOW					(V_{CC}) Gnd
			V_{IHmax}	V_{ILmin}	V_{IHAmin}	V_{ILAmax}	V_{EE}	
Power Supply Drain Current	I_E	8	4,5,6,7,9 10,11,12 13,14				8	1, 16
Input Current	I_{inH}	4	4				8	1, 16
	I_{inL}	4		4			8	1, 16
Output Voltage Logic 1	V_{OH}	3					8	1, 16
Output Voltage Logic 0	V_{OL}	3	4,5,6,7 9,12				8	1, 16
Threshold Voltage Logic 1	V_{OHA}	3				4,5,6,7	8	1, 16
Threshold Voltage Logic 0	V_{OLA}	3	9,12		4,5,6,7		8	1, 16
Switching Times (50Ω Load)					**Pulse In**	**Pulse Out**	**–3.2 V**	**+2.0 V**
Propagation Delay	t_{4+3-}	3			4	3	8	1, 16
	t_{4-3+}	3			4	3	8	1, 16
Rise Time (20 to 80%)	t_{3+}	3			4	3	8	1, 16
Fall Time (20 to 80%)	t_{3-}	3			4	3	8	1, 16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

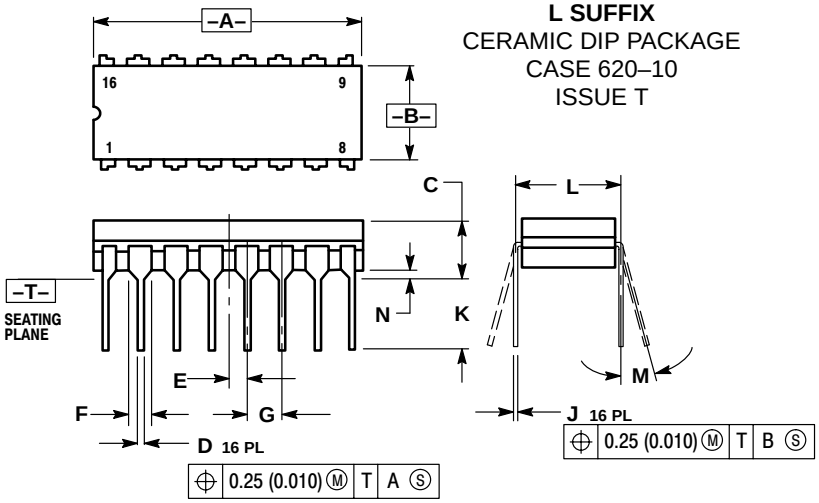
PLCC–20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775–02
ISSUE C



NOTES:
1. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

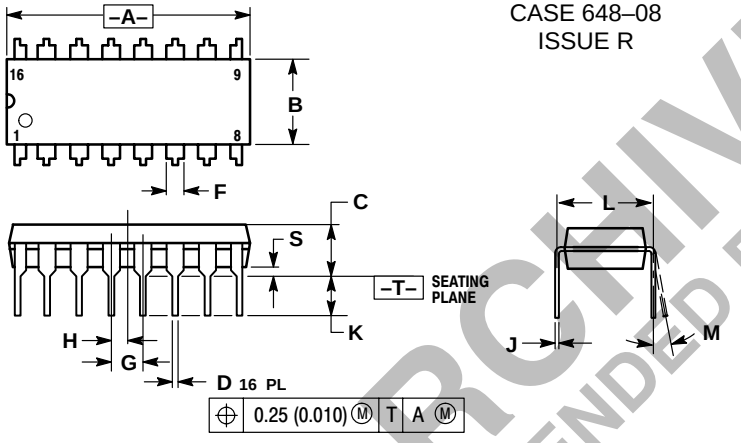
CDIP–16
L SUFFIX
CERAMIC DIP PACKAGE
CASE 620–10
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.020	0.040	0.51	1.01

PDIP–16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

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